



WAFER MAGAZINE

For more than twenty years, we have been developing innovative, highly efficient automation solutions that have proven themselves around the world. Thanks to our years of experience in basic technologies such as control technology, we can also turn highly complex customer requirements into solutions that pay off.

In order to make the manufacture of solar cells a competitive business, a high level of automation in the production plants is essential. Efficient, fully automated linking of the individual process steps helps to significantly increase the output per hour. Our product portfolio covers the Jonas & Redmann Wafer Magazine. This component is applicable to transportation and storage tasks and has been specially developed for implementation in PV production plants.

- Specially developed for implementation in PV-production plants
- Constantly improved to achieve highly gentle wafer transport and storage
- Proven construction prevents wafer breakage and reduces the impact of mechanical forces
- Excellent connectivity with any process equipment
- State-of-the-art production control by tracking via transponder chips

Jonas & Redmann

Wafer Magazine

The Jonas & Redmann Wafer Magazine is used for stacking raw wafers in preparation for processing. Therefore, wafers are taken manually out of their shipment boxes and stacked into the magazine. The magazine can be separated into two parts to enable stacking from the side. Thus wafer piles can easily be stacked without damaging wafer edges.

Within the magazine the base plate is raised when unloading wafers. Plastic belts on the magazine sides move the wafers upwards. When being unloaded wafers are gently lifted one by one (e.g. with a vacuum gripper) and then supplied to the aligned production equipment.

TECHNICAL DATA

capacity	600 wafers
materials	aluminium hardcoated, POM, rubber
tare weight	3 kg
wafer size	125 / 156
wafer thickness	130-240 µm

OPTIONS AND FEATURES

reduces impact of mechanical forces to wafers

prevents wafer bending

transponder chips are possible on 2 sides

reduces wafer breakage risk

protects wafers against vibrations

belt construction preventing wafer breakage by attrition